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Speech subject： Glass Core Substrate: Next Gen Advanced Packaging Technology

Speech leader: Jiamiao TANG, General Manager of AKMMV FCBGA, AKM Meadville Electronics (Xiamen) Co., Ltd.

Speech Description/Objective:

The glass base ABF substrate uses silicon base glass as the core substrate, which solves the industry pain point of organic substrate warping. The advantages of glass-based ABF substrate are significant, with minimal expansion and contraction deformation at high temperatures, reducing graphic distortion by 50%, and providing the dimensional stability required for tight layer-to-layer direct stacking interconnections. The interconnection density of glass substrate can be increased by up to 10 times; the mechanical performance of glass substrate is improved, enabling the realization of large-size, high-assembly-yield external packaging. Glass substrate provides greater flexibility in design rules for power transmission and signal routing. It can seamlessly integrate with optical components and embed sensors and capacitors into glass substrate at higher temperature processes, offering better power transmission solutions. Due to the above advantages of glass substrate, it is very suitable for chiplet application scenarios of high density and high computing power, and can meet the needs of chiplet high computing power chip. As a leading domestic company in the field of package substrate, AKMMV has conducted in-depth research on glass-based ABF substrate technology, contributing to the development and ecological chain construction of glass-based ABF carrier board technology by promoting cluster development, chain development, and collaborative development.

Speech Outline:

1. Xiamen site view and capacity introduction
2. The advantages and technological capability of glass core substrate
3. Next generation of glass core

Who Should Attend:

1. Professionals in the electronic packaging industry, including packaging engineers, technical R&D personnel, etc.
2. Relevant practitioners in the semiconductor industry, such as chip designers, manufacturing engineers, etc.
3. People who are interested in the application scenarios of high-density and high-computing power chips.
4. Scholars and researchers who focus on the development of glass-based ABF substrate technology.
5. Management personnel and decision-makers of related enterprises to understand industry trends and technological development directions.

Introduction of Speaker:

Long-term work in multinational companies and engage in ABF high-end substrate research and development, factory construction and large-scale production.With over twenty years of experience in the field of high-density ABF substrate for computer CPU chips, server chips, EMIB,

glass and ceramic related to high-computing chips. In the past six years, he led the establishment of two intelligent factories dedicated to ABF substrate for Intel, guiding the company growing out of nothing, and being a leading factory in the global industry from weak in technology. Received the Intel Global Technology and Manufacturing Achievement Award. Granted 18 international patents and more than 20 articles and 4 Intel trade secrets.